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Modular order for the development of mechanical structures for electronic equipment practices –

Part 2-3: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Extended detail specification – Dimensions for subracks, chassis, backplanes, front panels and plug-in units

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CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISION

MODULAR ORDER FOR THE DEVELOPMENT OF MECHANICAL STRUCTURES FOR ELECTRONIC EQUIPMENT PRACTICES –

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FOREWORD

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International Standard IEC 60917-2-3 has been prepared by subcommittee 48D: Mechanical structures for electronic equipment, of IEC technical committee 48: Electromechanical components and mechanical structures for electronic equipment.

The text of this standard is based on following documents:

FDIS	Report on voting
48D/338/FDIS	48D/342/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

IEC 60917 consists of the following parts, under the general title *Modular order for the development of mechanical structures for electronic equipment practices:*

Part 1: Generic standard

Part 2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice

Part 2-1: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Detail specification – Dimensions for cabinets and racks

Part 2-2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Detail specification – Dimensions for subracks, chassis, backplanes, front panels and plug-in units

Part 2-3: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Extended detail specification – Dimensions for subracks, chassis, backplanes, front panels and plug-in units

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

The dimensions in the detail specification for the 25 mm equipment practice standard are laid down in the IEC 60917-2 series.

Significant progress in electronics circuitry, with increasing signal speed and the demand for high availability of the electronics systems, has made an impact on the structural parts of the equipment, as specified in IEC 60917-2-2.

a) Considerations on the general tendency of the enclosure system

At the moment, the general tendencies of the enclosure system for telecom/IT equipment application and associated application are considered to be:

– the changing form of conventional centralized networking for telecommunication to flexible distributed networking to realize ubiquitous communication and computing environment by broad-band/IP and photonics-networking-based technology;

– flexible configuration of networking equipment from the open market is requested;

– a scalable and high-performance packaging/enclosure system is requested for new networking equipment;

– in addition, such a packaging/enclosure system will be widely applied for general electronic equipment, because IP networking technology is becoming one of the common interfaces for all of industrial systems.

Consequently, the following general requirements for the new enclosure system arise.

– Standard-based but various sized networking/IT equipment from the open market should be installed in one cabinet (see figure 1).

– The mass volume of copper/optical cables from the equipment should be managed in the cabinet.

– Networking/IT cabinets will be increasingly sited at general offices in enterprise buildings rather than at traditional technical rooms in telecom-central offices.

In order to meet these market needs, the implementation of additional specified dimensions for extended features based on IEC 60917-2-2 became necessary.

b) Subject for development of extended connector application packaging based on IEC 60917 series

The existing IEC 60917 series, which is structured on the modular concept of 25 mm, is based on the IEC standardized metric connector. However, the system packaging uses to many non-standardized enhanced connectors, which are necessary to realize the system functions and level of performance (see Figure 2).

NOTE IEC Subcommittee 48D, Working Group 2, reviews the trends in system packaging, in which key elements are electrical/optical signal interfaces and connectors, as well as the general tendency of the new enclosure system. From these aspects, the IEC Subcommittee 48D, Working Group 2 has recently developed IEC 60917-2-3 which will be applicable to system packaging for high-speed and other system applications in the near future.

MODULAR ORDER FOR THE DEVELOPMENT OF MECHANICAL STRUCTURES FOR ELECTRONIC EQUIPMENT PRACTICES –

Part 2-3: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Extended detail specification – Dimensions for subracks, chassis, backplanes, front panels and plug-in units

1 Scope and object

This part of IEC 60917 provides additional dimensions for a modular range of subracks and associated plug-in units based on IEC 60917-2-2.

A typical subrack consists of a frame design with mounting dimensions for installation into racks or cabinets in accordance with IEC 60917-2-1. The aperture dimensions of a subrack are specified in order to meet the mounting dimensions of front plug-in units.

This part of IEC 60917 comprises

– additional dimensions for subracks and subrack associated plug-in units with injector/ extractor handle;
– dimensions for basic electromagnetic shielding provisions;
– dimensions of the key/coding system for subrack and plug-in units;
– dimensions of the alignment pin for front panel and plug-in unit;
– dimensions of electrostatic discharge provisions;
– dimensions of rear-mounted plug-in units.

Connector-related dimensions are given in Annex A.

In order to ensure the compatibility of plug-in units into the subrack, inspection dimensions and connector-dependent dimensions are defined.

NOTE The drawings used in this part of IEC 60917 are not intended to indicate product design, only the specific dimensions that are used.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60917-1:1998, *Modular order for the development of mechanical structures for electronic equipment practices – Part 1: Generic standard*

IEC 60917-2-1:1993, *Modular order for the development of mechanical structures for electronic equipment practice – Part 2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Section 1: Detail specification – Dimensions for cabinets and racks*

IEC 60917-2-2:1994, *Modular order for the development of mechanical structures for electronic equipment practice – Part 2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Section 2: Detail specification – Dimensions for subracks, chassis, backplanes, front panels and plug-in units*

IEC 61076-4-100:2001, *Connectors for electronic equipment – Part 4-100: Printed board connectors with assessed quality – Detail specification for two-part connector modules having a grid of 2,5 mm for printed boards and backplanes*

IEC 61076-4-101:2001, *Connectors for electronic equipment – Part 4-101: Printed board connectors with assessed quality – Detail specification for two-part connector modules, having a basic grid of 2,0 mm for printed boards and backplane in accordance with IEC 60917*

IEC 61076-4-104:1999, *Connectors for use in d.c., low frequency analogue and digital high speed data application – Part 4-104: Printed board connectors with assessed quality – Detail specification for two-part modular connectors, basic grid of 2,0 mm, with terminations on a multiple grid of 0,5 mm*